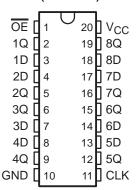
SCLS141E - DECEMBER 1982 - REVISED AUGUST 2003

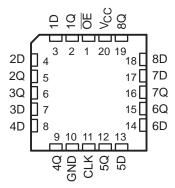
- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State True Outputs Can Drive Up To 15 LSTTL Loads
- Eight D-Type Flip-Flops in a Single Package
- Full Parallel Access for Loading

SN54HC374 . . . J OR W PACKAGE SN74HC374 . . . DB, DW, N, NS, OR PW PACKAGE (TOP VIEW)



- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 14 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max

SN54HC374...FK PACKAGE (TOP VIEW)



description/ordering information

These 8-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight flip-flops of the 'HC374 devices are edge-triggered D-type flip-flops. On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels that were set up at the data (D) inputs.

An output-enable (\overline{OE}) input places the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 20	SN74HC374N	SN74HC374N
	2010 DW	Tube of 25	SN74HC374DW	110074
	SOIC - DW	Reel of 2000	SN74HC374DWR	HC374
-40°C to 85°C	SOP - NS	Reel of 2000	SN74HC374NSR	HC374
	SSOP - DB	Reel of 2000	SN74HC374DBR	HC374
	T000D DW	Tube of 2000	SN74HC374PWR	110074
	TSSOP – PW	Reel of 250	SN74HC374PWT	HC374
	CDIP – J	Tube of 20	SNJ54HC374J	SNJ54HC374J
-55°C to 125°C	CFP – W	Tube of 85	SNJ54HC374W	SNJ54HC374W
	LCCC – FK	Tube of 55	SNJ54HC374FK	SNJ54HC374FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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processing does not necessarily include testing of all pa

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description/ordering information (continued)

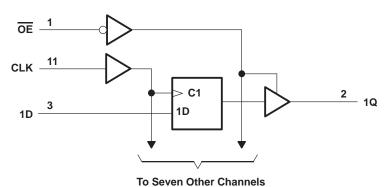
OE does not affect the internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

FUNCTION TABLE (each flip-flop)

	INPUTS		OUTPUT
OE	CLK	D	Q
L	↑	Н	Н
L	\uparrow	L	L
L	H or L	Χ	Q ₀
Н	Χ	Χ	Z

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}	-0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	
Continuous current through V _{CC} or GND	±70 mA
Package thermal impedance, θ _{JA} (see Note 2): DB package	70°C/W
DW package	58°C/W
N package	69°C/W
NS package	60°C/W
PW package	83°C/W
Storage temperature range, T _{stg} 6	35°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 3)

			SI SI	SN54HC374		SN	174HC37	' 4		
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
VCC	Supply voltage		2	5	6	2	5	6	V	
		V _{CC} = 2 V	1.5			1.5				
VIH	High-level input voltage	V _{CC} = 4.5 V	3.15			3.15			V	
		V _{CC} = 6 V	4.2			4.2				
	Low-level input voltage	V _{CC} = 2 V			0.5			0.5	V	
VIL		V _{CC} = 4.5 V			1.35			1.35		
		VCC = 6 V			1.8			1.8		
VI	Input voltage		0		VCC	0		VCC	V	
VO	Output voltage		0		VCC	0		VCC	V	
		V _{CC} = 2 V			1000			1000		
Δt/Δν	Input transition rise/fall time	V _{CC} = 4.5 V			500			500	ns	
		VCC = 6 V			400			400		
TA	Operating free-air temperature		-55		125	-40		85	°C	

NOTE 3: All unused inputs of the device must be held at VCC or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEST CONDITIONS		.,	Т	A = 25°C	;	SN54H	IC374	SN74HC374		
PARAMETER			VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4		
Voн	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
	V_{OL} $V_{I} = V_{IH} \text{ or } V_{IL}$	I _{OL} = 20 μA	2 V		0.002	0.1		0.1		0.1	
			4.5 V		0.001	0.1		0.1		0.1	
V _{OL}			6 V		0.001	0.1		0.1		0.1	V
		I _{OL} = 6 mA	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 7.8 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
loz	VO = VCC or 0		6 V		±0.01	±0.5		±10		±5	μΑ
Icc	$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
C _i			2 V to 6 V		3	10		10		10	pF

SN54HC374, SN74HC374 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		ļ ,,	T _A = 2	25°C	SN54H	IC374	SN74H	IC374	
		VCC	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
		2 V		6		4		5	
fclock	Clock frequency	4.5 V		30		20		24	MHz
		6 V		35		24		28	
		2 V	80		120		100		
t _w	Pulse duration, CLK high or low	4.5 V	16		24		20		ns
		6 V	14		20		17		
		2 V	100		150		125		
tsu	Setup time, data before CLK↑	4.5 V	20		30		25		ns
		6 V	17		25		21		
	Hold time, data after CLK↑	2 V	10		13		12		ns
th		4.5 V	5		5		5		
		6 V	5		5		5	·	

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

	FROM	то	.,	T,	Δ = 25°C	;	SN54H	IC374	SN74H	IC374	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	6	12		4		5		
f _{max}			4.5 V	30	60		20		24		MHz
			6 V	35	70		24		28		
			2 V		63	180		270		225	
^t pd	CLK	Any Q	4.5 V		17	36		54		45	ns
·			6 V		15	31		46		38	
			2 V		60	150		225		190	
t _{en}	ŌĒ	Any Q	4.5 V		16	30		45		38	ns
			6 V		14	26		38		32	
			2 V		36	150		225		190	
^t dis	ŌĒ	Any Q	4.5 V		17	30		45		38	ns
			6 V		16	26		38		32	
			2 V		28	60		90		75	
t _t		Any Q	4.5 V		8	12		18		15	ns
			6 V		6	10		15		13	

SN54HC374, SN74HC374 **OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS** WITH 3-STATE OUTPUTS SCLS141E - DECEMBER 1982 - REVISED AUGUST 2003

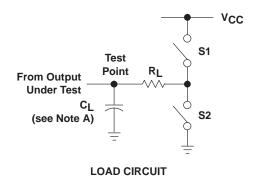
switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 1)

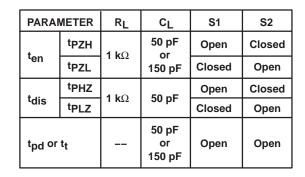
	FROM	то	.,	T,	ղ = 25°C	;	SN54H	C374	SN74HC374		
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	6	12				5		
fmax			4.5 V	30	60				24		MHz
			6 V	35	70				28		
		CLK Any Q	2 V		80	230		345		290	
t _{pd}	CLK		4.5 V		22	46		69		58	ns
· ·			6 V		19	39		58		49	
			2 V		70	200		300		250	
t _{en}	ŌĒ	Any Q	4.5 V		25	40		60		50	ns
		-	6 V		22	34		51		43	
	Any		2 V		45	210		315		265	- I
t _t		Any Q	4.5 V		17	42		63		53	
				6 V		13	36		53	_	45

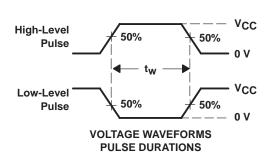
operating characteristics, $T_A = 25^{\circ}C$

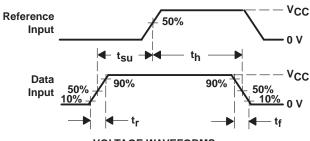
		PARAMETER	TEST CONDITIONS	TYP	UNIT
Г	C _{pd}	Power dissipation capacitance per flip-flop	No load	100	pF

PARAMETER MEASUREMENT INFORMATION

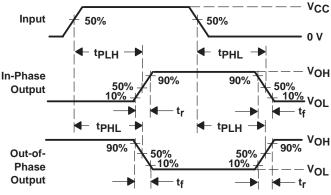


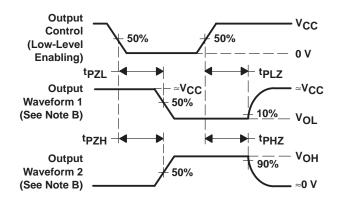






VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES





VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns, t_f = 6 ns.
- D. For clock inputs, $f_{\mbox{max}}$ is measured when the input duty cycle is 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLz and tpHz are the same as tdis.
- G. tpzL and tpzH are the same as ten.
- H. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



14 LEADS SHOWN

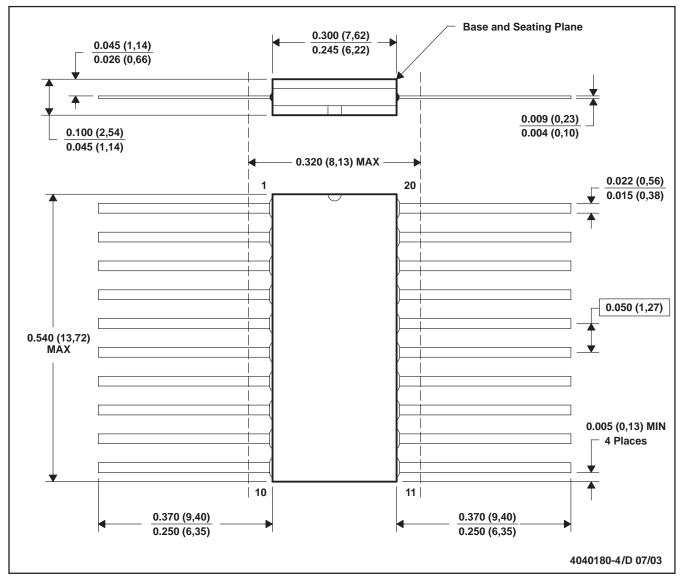


NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



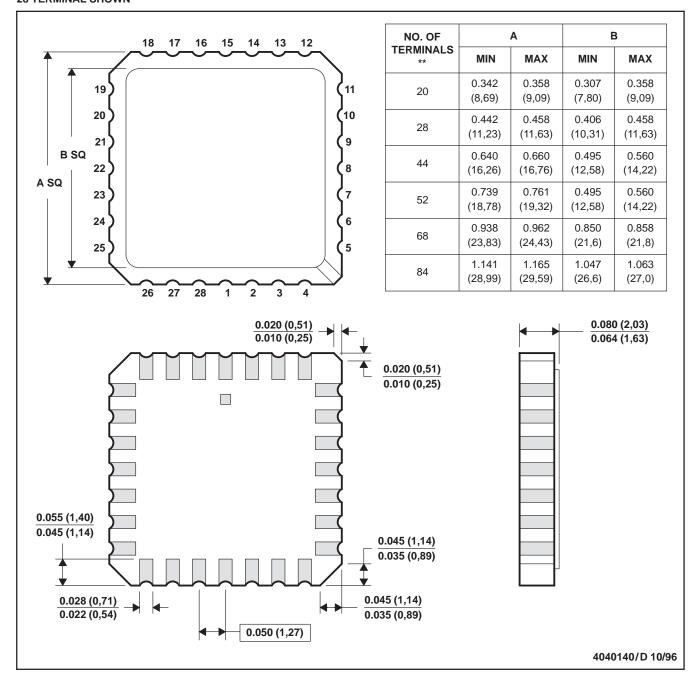
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



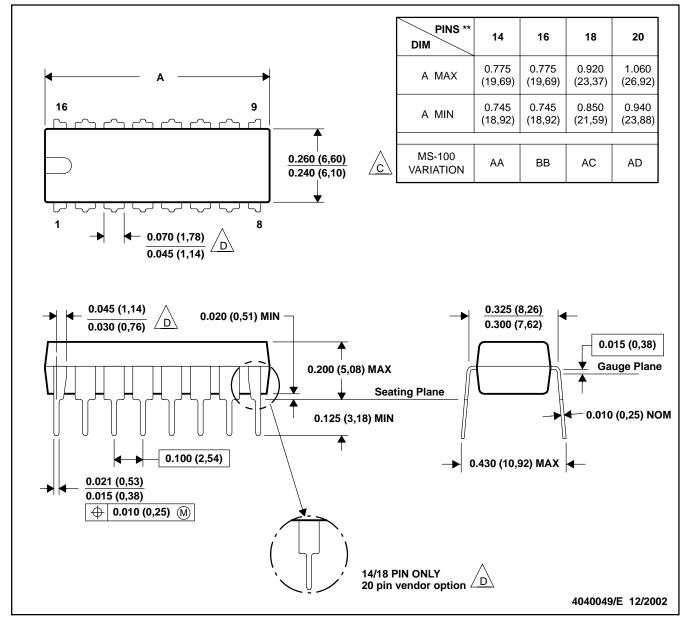
- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004



N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

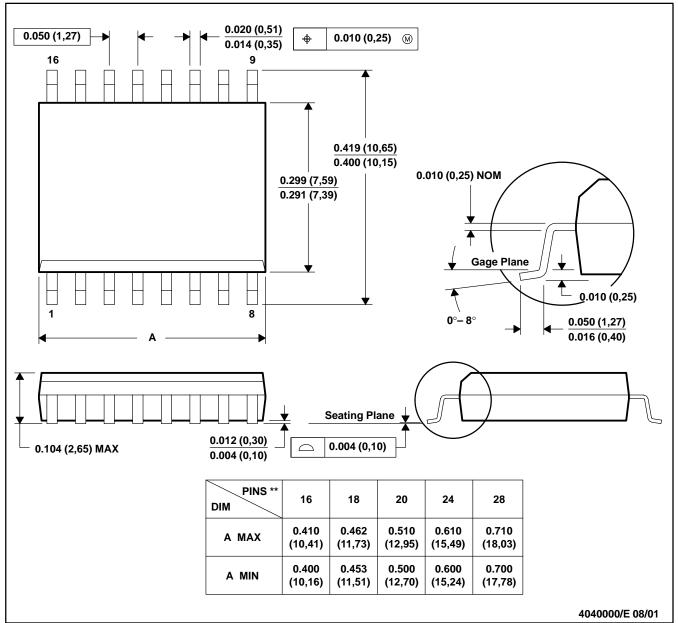
Falls within JEDEC MS-001, except 18 and 20 pin minimum body Irngth (Dim A).

The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

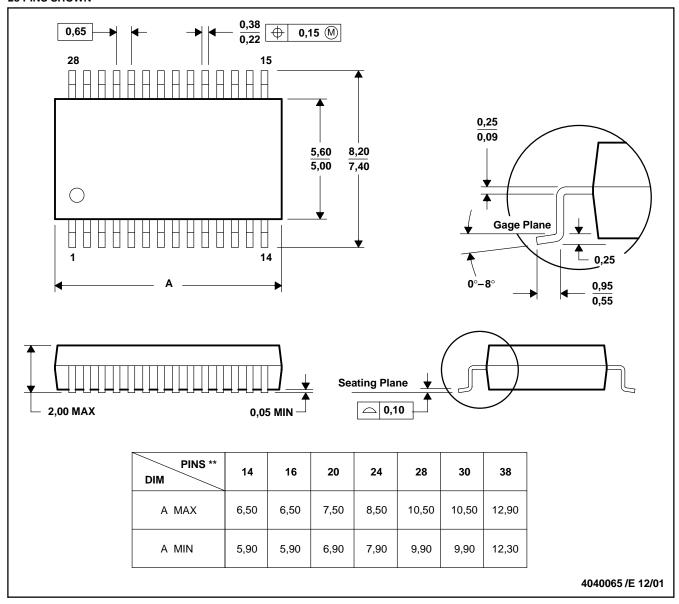
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

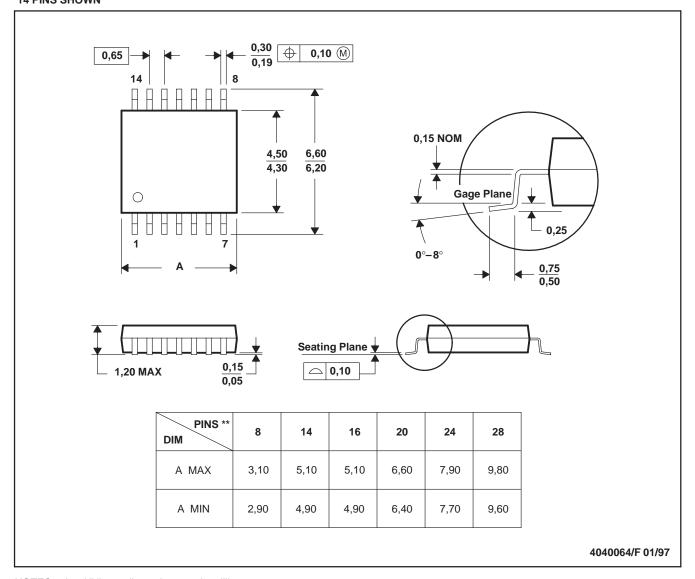
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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